

CHAD WaferMate300™

Automate Your Wafer Level Process

The Chad **WaferMate300™** is a highly configurable BOLTS compatible robotic wafer-handling cell that mates high performance with cost competitiveness.

The **WaferMate300™** pairs expertly with all types of process tools and environments. For BEOL (back-end-of-the-line) such as wafer level packaging, the **WaferMate300™** is configured with side handoff for traditional conveyor-style layouts such as screen printers, bonders, dispensers, inspection and plasma tools. CHAD's systems are often paired with more than one tool.

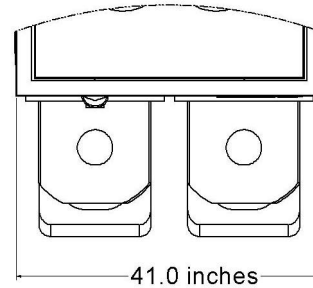


As a class-1 clean FEOL (front-end-of-the-line) EFEM, the **WaferMate300™** includes all applicable mini-environment components, E84 compliance, and rear hand-off.

CHAD's systems are made highly effective with **WaferWare™**, a third-generation, flexible software suite that allows wide-ranging application and GUI control.

At time of order, the **WaferMate300™** is configurable for 1-4 BOLTS interfaces, handoff location(s), MMI location(s) and a host of other mechanical, electrical, and software options and accessories.

CHAD's highly responsive project and engineering teams typically guide the specification process, and develop geometry and throughput models to meet each system's specific needs. This approach allows for optimized space, throughput and cost efficiency.



The **WaferMate300™** features super reliable, absolute encoder, 4-axis robots that can access up to 4 FOUPs without a linear track. This reduces cost and system complexity. These robots utilize fluid-magnetic seals, which provide stand-alone ISO class-1 cleanliness, and enjoy a worldwide install base in the tens of thousands. Configurations include dual-arm, split arm and wrist axis.

The robots are fitted with a range of end effector technologies, including vacuum, Bernoulli, edge grip and special components for thin or warped wafers. Robot mounted thru-beam mappers and reflective mappers are also deployed.

The **WaferMate300™** is a 300mm automation platform that can be adapted for 200mm and smaller substrates with the addition of CHAD's cassette shelf module, CHAD's **SMIF-EZ™** pod opener for SMIF environments, or FOUP bridge tools.

FOR MORE INFORMATION:

Chad Industries, Inc.
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Anaheim, CA 92806

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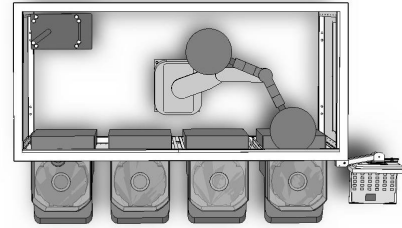


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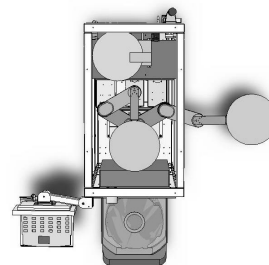
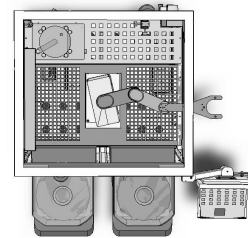
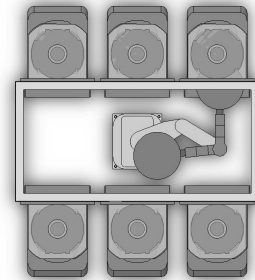
Performance Specifications

- Wafer alignment to +/- .05°
- Wafer Placement +/- 50µm
- 180 wafers per hour
- Up to ISO class 1 (optional)
- Full SEMI compliance
- MTBF 60,000 hrs



Standard Accessories

- FOUP Opener
- SMIF pod Opener
- Aligner
- OCR
- Barcode
- RFID
- Mini environment
- Ionization bars
- Wafer flip module
- DEK compatible Transfer Station
- Wafer Conveyor / oven interface
- SMEMA interface
- SECS/GEM interface
- See CHAD's 'Robotic Wafer Handler Worksheet' for full options listing. Available online at www.chadindustries.net



Facilities Requirements (approximate)

- 220VAC +/- 10% @ 50/60 Hz
Single Phase 3 wire
- 20 amps
- VAC 24mmHG @ 1lpm (and/or)
- CDA 90psi @ 2lpm

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